

Attorney's Docket No.: 10417-039001 / F51-125462M/HW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Toshimitsu Taniguchi et al. Serial No.: 09/652,044 J

Art Unit : 2811

Examiner: Samuel A. Gebremariam

Filed Title

: August 31, 2000

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING

THEREOF

Commissioner for Patents Washington, D.C. 20231

RESPONSE

In response to the action mailed June 5, 2002, please amend the application as follows: (unamended claims appear in small print and italics for ease of reference):

In the claims:

Please amend claims 6-8, 10-19, 22-24, 27-28 as follows:

--6. (Amended) A method of manufacturing a semiconductor device comprising:

forming high condentration source/drain layers of the reverse conductive type in a semiconductor layer of one conductive type;

forming a gate electrode on a channel layer located between the source and drain layers; and

forming a body layer of one conductive type adjacent to the source layer and a low concentration drain layer of the reverse conductive type formed between the channel layer and the drain/layer, wherein the body layer is formed only under the gate electrode. and wherein forming a body layer of one conductive type comprises doping impurities of one conductive type into said semiconductor layer by ion implantation.--

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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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